

# EMB-852T

Compact Board. Intel Celeron(R) Processor 600 MHz (100x6.0)

## Thermal Image Analysis Report

Report No: 05E080017

Release Date: MAY 5, 2005

2005/05/05  
Issue Stamp

Wenyuan Yang  
Manager

Ryan Cheng  
Test Engineer

## Thermal Image Analysis

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**I . Model Name :EMB-852T-A03**

**II . Description: EMB-852T.Rev.A0.3.W/600MHZ CPU.CFD.TOUCH  
(BIOS Rev: 1.0 (03/24/2005 ))**

**III. Date: May 05, 2005**

**IV. Measure Site: AAEON QE Dept.**

**V. Issued by : Ryan Cheng**

**VI.Equipment:**

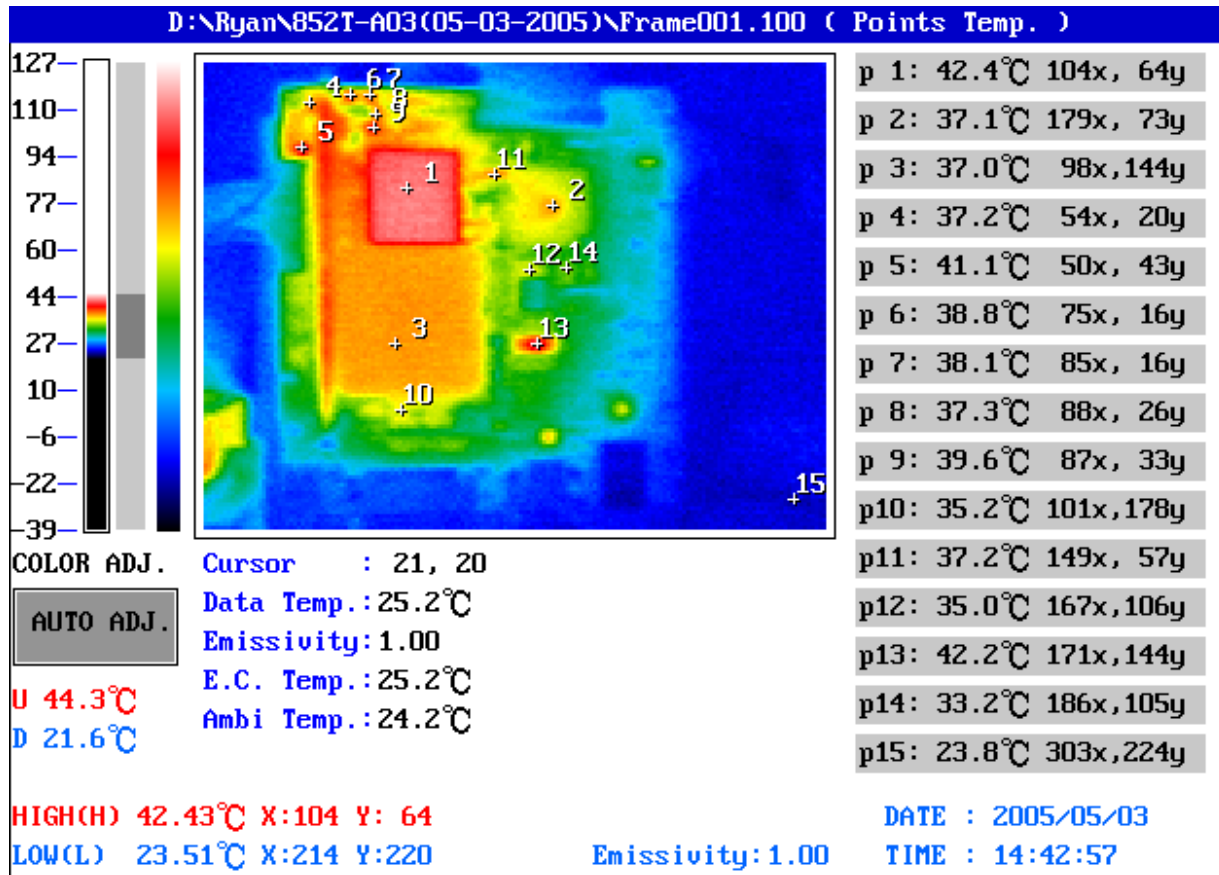
**1. TVS-100 series by NIPPON AVIONICS CO., LTD.**

**VII. Simulation Environment:**

- **Temperature: Component Side (1) : 23.8 °C  
Component Side (2) : 23.8 °C  
Solder Side (1) : 24.2 °C  
Solder Side (2) : 24.2 °C**
- **CPU: On Board CPU Intel Celeron(R) Processor 600 MHz (100x6.0)**
- **RAM: SAMSUNG / K4H560438E-GCCC / DDR400 / 1024MB / RR-200402**
- **Application Software: Run HCT (9.5)System Stress Test under Win2000 Professional+SP4**
- **Take Picture Time: After Power on 2 hours.**

### Temperature Profile Test:

Component Side (1) :



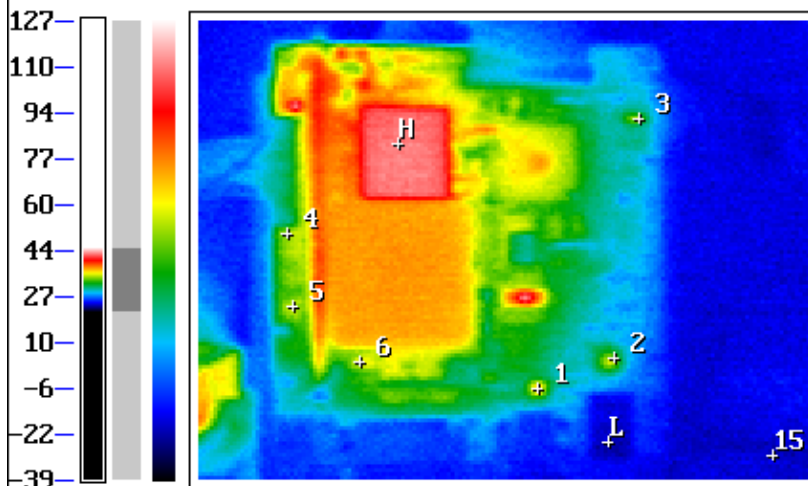
Point	Position	Describe	Tc	Tm (25°C)	Tm (60°C)	Note
1	U24	IC.SMD.BGA732.Chipset.NB82852GM.Intel.RG82852GM-SL6ZK	0~105°C	42.4°C	78.6°C	
2	U25	IC.SMD.Chipset ICH4.INTEL.FW82801DB SL6DM	0~110°C	37.1°C	73.3°C	
3	U23	INTEL CPU.Celeron-M.ULV 600MHz.Zero Cache.mFCBGA479	0~100°C	37.0°C	73.2°C	
4	TC28	KO-CAP.150uF.6.3V.20%.V(7.3*4.3*1.9mm).45mOhm SMD.KEMET.T520V157M006ASE045	N/A	37.2°C	73.4°C	
5	U13	REG.SMD SOP-8.2A Bus Termination Regulator.Winbond.W83310S-R2	-30~100°C	41.1°C	77.3°C	
6	U10	PWR.SMD.SO-8.N-Channel.30V.10A.13.5mΩ.MOSFET.APEC.AP4410M	-30~125°C	38.8°C	75°C	
7	U54	IC.SMD SO8.ACPI Power Controller.Intersil.ISL6506BCB	-30~100°C	38.1°C	74.3°C	
8	Q46	PWR.SMD.TO-252.N-Channel Power 25V 60A MOSFET.APEC.AP70T03H	-30~150°C	37.3°C	73.5°C	
9	U11	IC.SMD.SO8.Step-Down DC/DC Controller.Anpec.APW7057	-30~100°C	39.6°C	75.8°C	
10	L5	COIL.0.8uH.SMD.12.5*12.5*5.6mm.DCR=2.5mohm I <sub>dc</sub> =27.2Amp. 震 元.CEP125U-0R8	-30~125°C	35.2°C	71.4	
11	U15	IC.SMD TSSOP-28.Dual Power Supply Controller.SEMTECH.SC1485ITSTR	-15~100°C	37.2°C	73.4°C	
12	U34	IC.SMD.QFP128P Super I/O.ITE.IT8712F/HX	-30~100°C	35.0°C	71.2°C	
13	U22	IC.SMD.SSOP 56PIN.CLOCK GENERATOR.ICS.ICS952601	115°C	42.2°C	78.4°C	
14	U57	(TF)IC.SMD SSOP 28P.RS232 Driver ESD 15KV.INTERSil.HIN213ECAZ	0~70°C	33.2°C	69.4°C	
15		Ambient Temperature		23.8°C		

1. Operation Temperature (°C):  
 Tc(Case temp.) = Ta(Ambient Temp.) +/- 30°C = Tj(Junction Temp.) +/- 25°C

**Note:** The description in red states which temperature is over the specification of the device.

**Temperature Profile Test:**

**Component Side (2) :**



p 1:	35.9°C	177x, 192y
p 2:	34.0°C	217x, 176y
p 3:	33.2°C	230x, 51y
p 4:	34.0°C	46x, 111y
p 5:	34.2°C	49x, 149y
p 6:	34.9°C	84x, 178y
p 7:		
p 8:		
p 9:		
p10:		
p11:		
p12:		
p13:		
p14:		
p15:	23.8°C	300x, 227y

COLOR ADJ. Cursor : 11, 14  
 Data Temp.: 25.0°C  
 Emissivity: 1.00  
 E.C. Temp.: 25.0°C  
 Ambi Temp.: 24.2°C

AUTO ADJ.  
 U 44.3°C  
 D 21.6°C

HIGH(H) 42.43°C X:104 Y: 64  
 LOW(L) 23.51°C X:214 Y:220

Emissivity: 1.00

DATE : 2005/05/03  
 TIME : 14:42:57

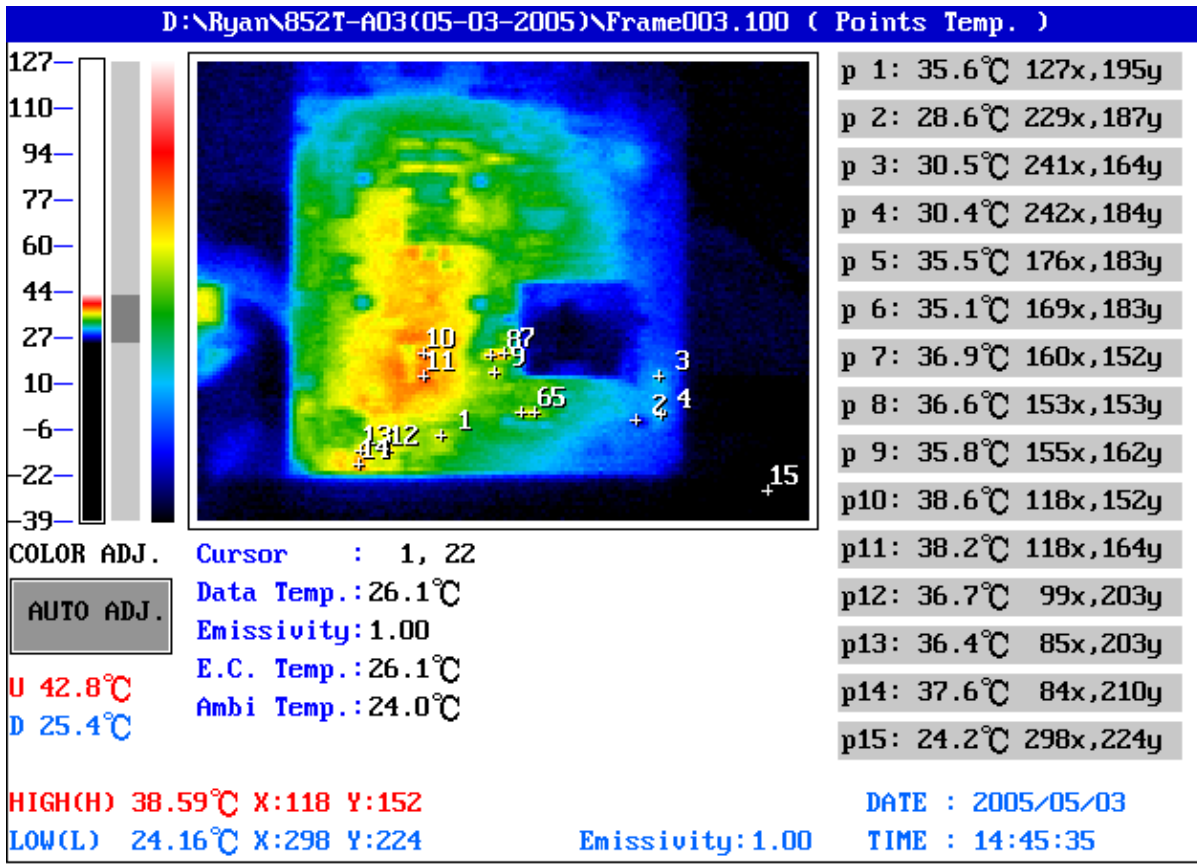
Point	Position	Describe	Tc	Tm (25°C)	Tm (60°C)	Note
1	U49	IC.SMD LQFP 48Pin.6 Channel AC'97 Audio Codec.REALTEK.ALC655	-30~100°C	35.9°C	72.1°C	
2	U28	IC.SMD.BGA 196P Ethernet Chipset.Intel.82562EZ	0~135°C	34.0°C	70.2°C	
3	U3	IC.SMD.SOIC 14P.TLSN7406	-30~100°C	33.2°C	69.4°C	
4	M2	PWR.SMD.SOP 8P.N & P-Channel Power MOSFET.APEC.AP4500M	-30~125°C	34.0°C	70.2°C	
5	U60	IC.SMD.TQFP.32P.Touch Screen Controller.光.DMC9000.Firmwa:E2.1(ATmega8)	-70~115°C	34.2°C	70.4°C	
6	U21	IC.SMD TSSOP-38 IMVP4.Dual Phase PWM Controller.SEMTECH.SC1476	-30~115°C	34.9°C	71.1°C	
7						
8						
9						
10						
11						
12						
13						
14						
15		Ambient Temperature		23.8°C		

1. Operation Temperature (°C):  
 $T_c(\text{Case temp.}) = T_a(\text{Ambient Temp.}) \pm 30^\circ\text{C} = T_j(\text{Junction Temp.}) \pm 25^\circ\text{C}$

**Note:** The description in red states which temperature is over the specification of the device.

### Temperature Profile Test:

#### Solder Side (1) :



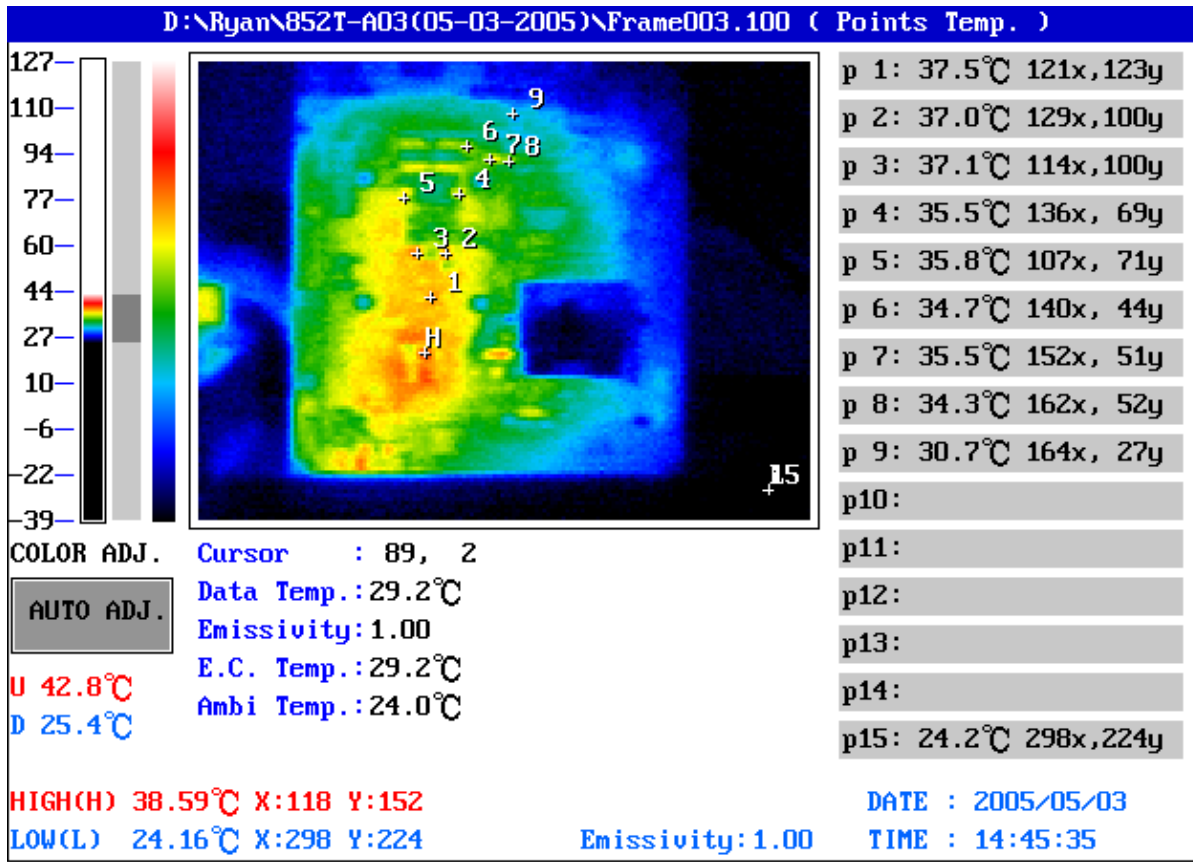
Point	Position	Describe	Tc	Tm (25°C)	Tm (60°C)	Note
1	U31	IC.SMD LQFP.64P DVI/TV ENCODER.CHRONTEL.CH7009A	-80~115°C	35.6°C	71.4°C	
2	U43	IC.SMD.LQFP.48P.LPC to 4 UART.FINTEK.F81216D	-30~100°C	28.6°C	64.4°C	
3	U45	(TF)IC.SMD SSOP 28P.RS232 Driver ESD 15KV.INTERSIL.HIN213ECAZ	0~70°C	30.5°C	66.3°C	
4	U44	(TF)IC.SMD SSOP 28P.RS232 Driver ESD 15KV.INTERSIL.HIN213ECAZ	0~70°C	30.4°C	66.2°C	
5	U14	Dual N-Channel.SMD SO-8.2.5V MOSFET.APEC.AP9926M	-30~125°C	35.5°C	71.3°C	
6	U18	PWR.SMD SO8.N-Channel MOSFET 30V 15A.FAIRCHILD.FDS7760A	-30~125°C	35.1°C	70.9°C	
7	U16	Dual N-Channel.SMD SO-8.2.5V MOSFET.APEC.AP9926M	-30~125°C	36.9°C	72.7°C	
8	U17	PWR.SMD SO8.N-Channel MOSFET 30V 15A.FAIRCHILD.FDS7760A	-30~125°C	36.6°C	72.4°C	
9	TC11	SP CAP.220uF.2V.-35~+10%.D(7.3*4.3*1.9mm).9mOhm SMD.Panasonic.EEFSX0D221YR	-40~105°C	35.8°C	71.6°C	
10	TC25	SP CAP.220uF.2V.-35~+10%.D(7.3*4.3*1.9mm).9mOhm SMD.Panasonic.EEFSX0D221YR	-40~105°C	38.6°C	74.4°C	
11	TC27	SP CAP.150uF.6.3V.20%.D(7.3*4.3*2.8mm).18mOhm SMD.Panasonic.ECGUD0J151R	-40~105°C	38.2°C	74°C	
12	U55	PWR.SMD SO-8.P-Channel 30V MOSFET.APEC.AP4435M	-30~125°C	36.7°C	72.5°C	
13	TC7	KO-CAP.330uF.6.3V.20%.D(7.3*4.3*2.8mm).45mOhm SMD.KEMET.T520D337M006AS	N/A	36.4°C	72.2°C	
14	U12	PWR.SMD.SO-8.N-Channel.30V.10A.13.5mΩ.MOSFET.APEC.AP4410M	-30~125°C	37.6°C	73.4°C	
15		Ambient Temperature		24.2°C		

1. Operation Temperature (°C):  
 $T_c(\text{Case temp.}) = T_a(\text{Ambient Temp.}) \pm 30^\circ\text{C} = T_j(\text{Junction Temp.}) \pm 25^\circ\text{C}$

**Note:** The description in red states which temperature is over the specification of the device.

### Temperature Profile Test:

#### Solder Side (2) :



Point	Position	Describe	Tc	Tm (25°C)	Tm (60°C)	Note
1	TC24	SP CAP.220uF.2V.-35~+10%.D(7.3*4.3*1.9mm).9mOhm SMD.Panasonic.EEFSX0D221YR	-40~105°C	37.5°C	73.3°C	
2	TC21	SP CAP.220uF.2V.-35~+10%.D(7.3*4.3*1.9mm).9mOhm SMD.Panasonic.EEFSX0D221YR	-40~105°C	37.0°C	72.8°C	
3	TC20	SP CAP.220uF.2V.-35~+10%.D(7.3*4.3*1.9mm).9mOhm SMD.Panasonic.EEFSX0D221YR	-40~105°C	37.1°C	72.9°C	
4	TC23	SP CAP.220uF.2V.-35~+10%.D(7.3*4.3*1.9mm).9mOhm SMD.Panasonic.EEFSX0D221YR	-40~105°C	35.5°C	71.3°C	
5	TC22	SP CAP.220uF.2V.-35~+10%.D(7.3*4.3*1.9mm).9mOhm SMD.Panasonic.EEFSX0D221YR	-40~105°C	35.8°C	71.6°C	
6	TC18	SP CAP.150uF.6.3V.20%.D(7.3*4.3*2.8mm).18mOhm SMD.Panasonic.ECGUD0J151R	-40~105°C	34.7°C	70.5°C	
7	U7	(TF)IC.SMD SOP.8Pin Switching PWM Controller.IR.IRU3037CSPbF	25~100°C	35.5°C	71.3°C	
8	U53	Dual N-Channel.SMD SO-8.2.5V MOSFET.APEC.AP9926M	-30~125°C	34.3°C	70.1°C	
9	TC33	SP CAP.150uF.6.3V.20%.D(7.3*4.3*2.8mm).18mOhm SMD.Panasonic.ECGUD0J151R	-40~105°C	30.7°C	66.5°C	
10						
11						
12						
13						
14						
15		Ambient Temperature		24.2°C		

1. Operation Temperature (°C):  
 $T_c(\text{Case temp.}) = T_a(\text{Ambient Temp.}) \pm 30^\circ\text{C} = T_j(\text{Junction Temp.}) \pm 25^\circ\text{C}$

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